

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Yonggang Li	09/28/2006
RECEIVING PARTY DATA	
Name:	Intel Corporation
Street Address:	2200 Mission College Boulevard
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95052
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11540074
CORRESPONDENCE DATA	
Fax Number:	(408)720-8383
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	4087208300
Email:	chester_vistan@bstz.com
Correspondent Name:	Blakely, Sokoloff, Taylor, & Zafman LLP
Address Line 1:	1279 Oakmead Parkway
Address Line 4:	Sunnyvale, CALIFORNIA 94085
ATTORNEY DOCKET NUMBER:	42P24941
NAME OF SUBMITTER:	Edwin H. Taylor Reg No. 25,129
Total Attachments: 2 source=P24941#page1.tif source=P24941#page2.tif	

CH \$40.00 11540074

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

Yonggang Li

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95052 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the application for the United States patent entitled:

Method of Providing Solder Bumps on a Substrate Using Localized Heating

the Declaration for which has been executed by the undersigned prior hereto or concurrently herewith, said patent application which can also be identified as follows (if necessary):

(I hereby authorize and request my attorney, associated with Customer Number 45209, to insert on the designated lines below, the filing date and application number of said application when known.)

United States Patent Application Number _____ filed on _____.

and in and to said application (nonprovisional or provisional) and all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all nonprovisional applications claiming priority to said application, and all other patent applications that have been or shall be filed in the United States and all foreign countries on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all foreign countries on said inventions and improvements; and in and to all rights of priority resulting from the filing of said United States applications;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents, on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

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covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Each Inventor please sign and Date below



INVENTOR 1

Yonggang Li



(Today's Date)